Printed Circuit Board order information	
Mechanical drawing and demension	
Main cut-out PCB	Rectangle / Square / Round
PCB dimension	70 x 70mm
PCB thickness	1.57 mm
PCB thickness Tolerance	+/-10%
PCB cut out	Board Outline
Drawing no.	n/a
PCB characteristics	
Substrate material	FR4 standard; er @ 1Ghz= 4.2-4.7 Tg=135
Layer number (Cu)	4
Finishing	Immersion Gold default (ENIG)
Nickel plating	4.0um minimum (default Immersion Gold)
Gold plating	0.05um minimum (default Immersion Gold)
Minimum conductor width	200um
Minimum spacing	100um
Absolute minimum land PAD	250um
Absolute minimum spacing	IPC
Copper thickness Outer layers	18um
Copper thickness Inner layers	18um
Copper Thieving allowed	No
Soldermask Topside	Yes
Soldermask Bottomside	Yes
Soldermask Color	Green
Soldermask Thickness	Standard
Soldermask Webs	Les than 75um can be removed
Silkscreen Topside	Yes
Silkscreen Bottomside	Yes
Silkscreen Color	White
Silkscreen Proces	Silkscreen (Default)
Silkscreen Clipping	On Soldermask
Countersunk Topside	No
Countersunk Bottomside	No
Partial plating Topside	No
Partial plating Bottomside	No
Milling Through	No
Milling Topside	No
Milling Bottomside	No
Shorts at Topside	Yes see drawing 195-10
Shorts at Bottomside	Yes see drawing 195-11
Counterbore at Top	No
Counterbore at Bottom	No
Dut area Top	No
Dut area Bottom	No
PB free logo allowed on Topside	Yes
UL code allowed on Topside	Yes

Bow and Twist Tolerance	0,75% (Using smd)
Maximum leakage current	n/a See Leakage Remark (Import text file)
Hole Diameter Tolerance Plated holes >0.5<=1.5mm +/- 0.1mm >1.5mm +/- 0.1mm Non plated holes >0.5<=1.5mm +/- 0.05mm >1.5mm +/- 0.1mm	Hole Location Tolerance Plated holes >0.5<=1.5mm +/- 0.1mm >1.5mm +/- 0.1mm Non plated holes >0.5<=1.5mm +/- 0.05mm >1.5mm +/- 0.1mm

Deliverables: (will always be delivered by pcb-supplier & send to NXP)

1. PCB test-report
2. Final pcb stackup

Requirements:

1. 100 % open & short electrical verification using supplied IPC-356 netlist.
2. Board should meet the latest revision of IPC-A-600 Class 2
   (Unless otherwise specified)

Remarks:

Via 1	SPECIFICATION
Size	0.2 mm
Via Type	PTH Via
Via Filling	None
Via Surface Plating	standard
Drill Table Chart	Top to Bottom
None Standard Colom in Drillchart	n/a

Via 2	SPECIFICATION
Size	0.15 mm
Via Type	PTH Microvia
Via Filling	Non-Conductive Epoxy
Via Surface Plating	Plated, Filled, Flat
Drill Table Chart	Top to Bottom
None Standard Colom in Drillchart	n/a

ECO NO.		DESIGN-FILE 7022-000-0076-R3-00.DSN						
NXP	TFA8200 Demobaord PCB Fabrication Info			7022-000-0077	1	2017-06-06		
NAME N.M. Laan	SUPERS.	GR.TOT. 4	GR.NO. 195- 01	PAGE. 1 OF 1	10	GHWE	A3	
DATA FMT BRDDOC	PROG CADENCE ALLEGRO		PLATF. MS WINDOWS		TEMPL-FILE			
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